

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YI-CHUAN TENG</td> <td>10/30/2013</td> </tr> <tr> <td>JUNG-HUEI PENG</td> <td>10/31/2013</td> </tr> <tr> <td>SHANG-YING TSAI</td> <td>10/30/2013</td> </tr> <tr> <td>LI-MIN HUNG</td> <td>10/30/2013</td> </tr> <tr> <td>YAO-TE HUANG</td> <td>10/30/2013</td> </tr> <tr> <td>CHIN-YI CHO</td> <td>10/30/2013</td> </tr> </tbody> </table>		Name	Execution Date	YI-CHUAN TENG	10/30/2013	JUNG-HUEI PENG	10/31/2013	SHANG-YING TSAI	10/30/2013	LI-MIN HUNG	10/30/2013	YAO-TE HUANG	10/30/2013	CHIN-YI CHO	10/30/2013
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YAO-TE HUANG	10/30/2013														
CHIN-YI CHO	10/30/2013														
RECEIVING PARTY DATA															
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.														
Street Address:	NO. 8, LI-HSIN RD. 6														
Internal Address:	HSIN-CHU SCIENCE PARK														
City:	HSIN-CHU														
State/Country:	TAIWAN														
Postal Code:	300-77														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14072141</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14072141										
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Application Number:	14072141														
CORRESPONDENCE DATA															
Fax Number:	(216)502-0601														
Phone:	216-502-0600														
Email:	docketing@eschweilerlaw.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	ESCHWEILER & ASSOCIATES, LLC.														
Address Line 1:	629 EUCLID AVENUE, SUITE 1000														
Address Line 2:	NATIONAL CITY BANK BUILDING														
Address Line 4:	CLEVELAND, OHIO 44114														
ATTORNEY DOCKET NUMBER:	TSMCP349US														
PATENT															

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NAME OF SUBMITTER:	THOMAS G. ESCHWEILER
Signature:	/Thomas G. Eschweiler/
Date:	11/05/2013
Total Attachments: 8 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif source=Assignment#page6.tif source=Assignment#page7.tif source=Assignment#page8.tif	

U.S. Patent Appln. No.

Docket No. TSMCP349US

Filing Date

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Yi-Chuan Teng
6F, No. 79, Jiaqin N. Rd.
Hsinchu County
Zhubei City 302
Taiwan (R.O.C.)

Assignor(s):

Jung-Huei Peng
7F-1, No. 6, Zihciang 6th St.
Hsinchu Hsien
Jhubei City
Taiwan (R.O.C.)

Assignor(s):

Shang-Ying Tsai
No. 110, Longjiang Rd.
Taoyuan County
Pingzhen City 324
Taiwan (R.O.C.)

Assignor(s):

Li-Min Hung
14F-5, No. 28, Bainian 3rd St.
Taoyuan County
Longtan Township 325
Taiwan (R.O.C.)

Assignor(s):

Yao-Te Huang
10F-3, No. 419-3, Sec. 2, Gongdao 5th Rd.
East District
Hsinchu City 300
Taiwan (R.O.C.)

Assignor(s):

Chin-Yi Cho
392-3, Cisian 1st Rd.
Sinsing District
Kaohsiung City
Taiwan (R.O.C.)

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Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled
"WAFER LEVEL PACKAGING TECHNIQUES" for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration and Power of
Attorney); or

was filed on _____ and accorded U.S. Serial No. _____; or

I hereby authorize and request my attorney associated with Customer No.
107476, to insert on the designated lines below the filing date and application
number of said application when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is
desirous of acquiring the entire right, title and interest in and to the invention and in and to
any letters patent that may be granted therefore in the United States and in any and all
foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of
which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto
ASSIGNEE its successors and assigns, the entire right, title and interest in and to said
invention and improvements, said application and any and all letters patent which may be

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granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

10/30/2013

Date

Yi-Chuan Teng

Name 1st Inventor Yi-Chuan Teng

TSMC Docket No. TSMC2013-0798

Docket No. TSMCP349US

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Filing Date

10/31/2013
Date

Jung-Huei Peng
Name 2nd Inventor Jung-Huei Peng

TSMC Docket No. TSMC2013-0798

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10/30/2013
Date

Shang Ying Tsai
Name 3rd Inventor Shang-Ying Tsai

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Filing Date

2013/10/20
Date

Li-Min Hung
Name 4th Inventor Li-Min Hung

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Docket No. TSMCP349US

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Filing Date

2013.10.30
Date

Yao-Te Huang
Name 5th Inventor Yao-Te Huang

TSMC Docket No. TSMC2013-0798

Docket No. TSMCP349US

U.S. Patent Appln. No.

Filing Date

10/30/2013

Date

Chin-Yi Cho.

Name 6th Inventor Chin-Yi Cho